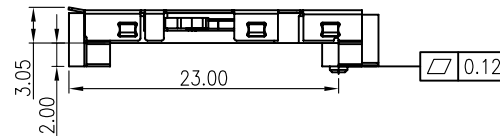
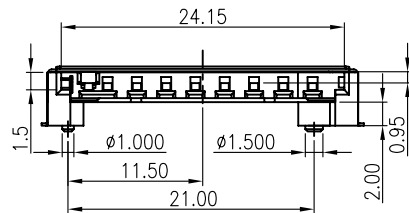


P.C.B Layout



SD CARD PIN DESIGN

Pin No.	Name	Description
1#	CD/DAT3	Card detect/Data I/O
2#	CMD	Command
3#	VSS1	Ground
4#	VDD	Power
5#	CLK	Clock
6#	VSS2	Ground
7#	DAT0	Data I/O
8#	DAT1	Data I/O
9#	DAT2	Data I/O

NOTES:

1.MATERIAL

HOUSING: HIGH TEMPERATURE THERMOPLASTIC.  
CONTACT: COPPER ALLOY.  
SHELL: COPPER ALLOY.

2.PLATING

CONTACT AREA: GOLD FLASH PLATED OVER Ni.  
SOLDER TAIL: 100  $\mu$ " MIN Sn/Pb PLATED OVER Ni.  
SHELL SOLDER AREA: GOLD PLATED OVER Ni.

3.RATING

CURRENT RATING: 0.5A  
VOLTAGE RATING: 250VRMS  
OPERATING TEMPERATURE: -25°C~90°C

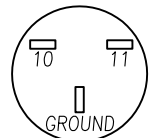
4.SPECIFICATION

CONTACT RESISTANCE: 40 Milliohms  
DIELECTRIC WITHSTANDING VOLTAGE: 500VAC Megohms  
INSULATION RESISTANCE: 100 Megohms  
INSERTION FORCE: 40N MAX.  
SEPARATION FORCE: 2N MIN.

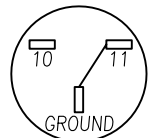
5.UNSPECIFIED TOLERANCE: .XXX  $\pm 0.10$

.XX  $\pm 0.25$

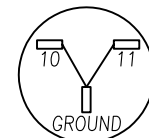
.X  $\pm 0.38$



WITHOUT CARD



CARD INSERTED  
WRITE PROTCT:LOCK



CARD INSERTED  
WRITE PROTECT:UNLOCK

10--WRITE PROTECT PIN  
11--CARD DETECT PIN  
GROUND(SHELL)--COMMON PIN

<b>XMULTIPLE</b>		CONNECTING THE INFORMATION AGE	
XMULTIPLE ASIA 4F, No. 347, Yang Guang St., Neihu Chiu, Taipei, Taiwan 11475		XMULTIPLE USA 543 Country Club Drive #B 128 Simi Valley, CA 93085	
THIS DRAWING IS A CONTROLLED DOCUMENT.		CUSTOMER/NO:	
TITLE: SECURE DIGITAL MEMORY CARD CONNECTOR, STANDOFF 2.00 TYPE		DWG NO: XSDC-0-09M1-WG50-10	
PART NO: XSDC-0-09M1-WG50-10		DRAWN: ANNIE	
		CHKD: JEFF	
		DATE: 09/11/04	
DIMENSIONS		SHEET	
mm[inch]		1 of 1	
		REV	
		01	